

FEATURES

- 72-pin industry standard 4-byte single-in-line memory module
- JEDEC compliant: 21-C, Fig. 4-18 A,B, Fig. 4-6 (Release 6) No.95 MO-116
- Supports 90°, 40° and 22.5° connectors
- High performance, CMOS
- Single 5V ± 10% power supply
- TTL-compatible inputs and outputs
- FAST PAGE MODE access cycle Refresh modes: RAS-ONLY, CAS-BEFORE-RAS, HIDDEN
- Refresh: 1024 refresh cycles every 16 ms
 Dimensions: 4.25" (length) x 1.00" (height) x 0.208" (max thickness)

PERFORMANCE RANGE

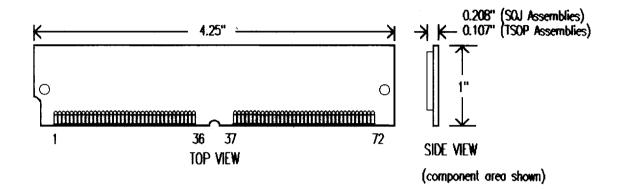
SYMBOL	PARAMETER	Re Stone	70 m
t _{RAC}	RAS Access Time	60 ns (max)	70 ns (max)
t _{CAC}	CAS Access Time	15 ns (max)	20 ns (max)
t _{AA}	Access Time from Column Address	30 ns (max)	35 ns (max)
t _{RC}	Random Read or Write Cycle Time	104 ns (min)	124 ns (min)
t _{PC}	Fast Page Mode Cycle Time	45 ns (min)	50 ns (min)

ORDERING INFORMATION

DESCRIPTION	PARE,	ENGINEERING DESCRIPTOR
1M x 32, 60 ns, Gold Tabs, SOJ	20024C	CL001E01320B0DJ-60
1M x 32, 60 ns, Gold Tabs, TSOP	20570C	CL001E01320B0DT-60
1M x 32, 60 ns, Tin-Lead Tabs, SOJ	9166C	CL001D01320B0DJ-60
1M x 32, 60 ns, Tin-Lead Tabs, TSOP	20571C	CL001D01320B0DT-60
1M x 32, 70 ns, Gold Tabs, SOJ	5508C	CL001E01320B0DJ-70
1M x 32, 70 ns, Gold Tabs, TSOP	20572C	CL001E01320B0DT-70
1M x 32, 70 ns, Tin-Lead Tabs, SOJ	5171C	CL001D01320B0DJ-70
1M x 32, 70 ns, Tin-Lead Tabs, TSOP	21029C	CL001D01320B0DT-70
1M x 32, 60 ns, Gold Tabs, SOJ	20112C	CL001E01320B0EJ-60
1M x 32, 60 ns, Tin-Lead Tabs, SOJ	20113C	CL001D01320B0EJ-60
1M x 32, 70 ns, Gold Tabs, SOJ	20114C	CL001E01320B0EJ-70
1M x 32, 70 ns, Tin-Lead Tabs, SOJ	20115C	CL001D01320B0EJ-70



CARD OUTLINE



GENERAL DESCRIPTION

The 1M x 32 SIMM uses dynamic RAM devices and is designed for use as a general-purpose 4-byte wide memory assembly with 8 data bits per byte. The SIMM is populated with eight 1M x 4 DRAMs.

Presence Detect (PD) bits provide information about SIMM density, addressing, performance and features. During Read or Write Cycles, each byte may be uniquely addressed via 20 address bits, with the first ten bits (A0~A9) latched on RAS and the latter ten bits (A0~A9) latched on CAS. READ or WRITE cycles are selected with the WE input, with a logic low indicating a WRITE cycle and a logic HIGH indicating a READ cycle. During a WRITE cycle, data-in is latched by the falling edge of WE or CAS, whichever occurs last.

FAST PAGE MODE operation allows for faster READs or WRITEs within a row-address-defined page boundary. A FAST PAGE MODE cycle is initiated with RAS followed by CAS, then strobing CAS to latch different column addresses while holding RAS LOW.

Returning RAS and CAS high terminates a memory cycle and returns the DRAMs to a reduced-current STANDBY state.

Memory cell data is retained in its correct state by maintaining power and executing any RAS cycle (READ, WRITE) or RAS refresh cycle (RAS-ONLY, CBR, or HIDDEN) so that all 1024 combinations of RAS addresses (A0~A9) are executed at least every 16 ms. The CBR refresh and HIDDEN Refresh cycles will invoke the on-chip refresh address counters for automatic RAS addressing.



PIN DESCRIPTION

RASO,RAS2	Row Address Strobe
CASO~CAS3	Column Address Strobe
WE	Write Enable
A0~A9	Address Inputs
DQ0~7,DQ9~16, DQ18~25,DQ27~34	Data In/Out
VCC	Power (+5.0V)
VSS	Ground
NC	No Connection
PD1~4	Presence Detects

PRESENCE DETECT

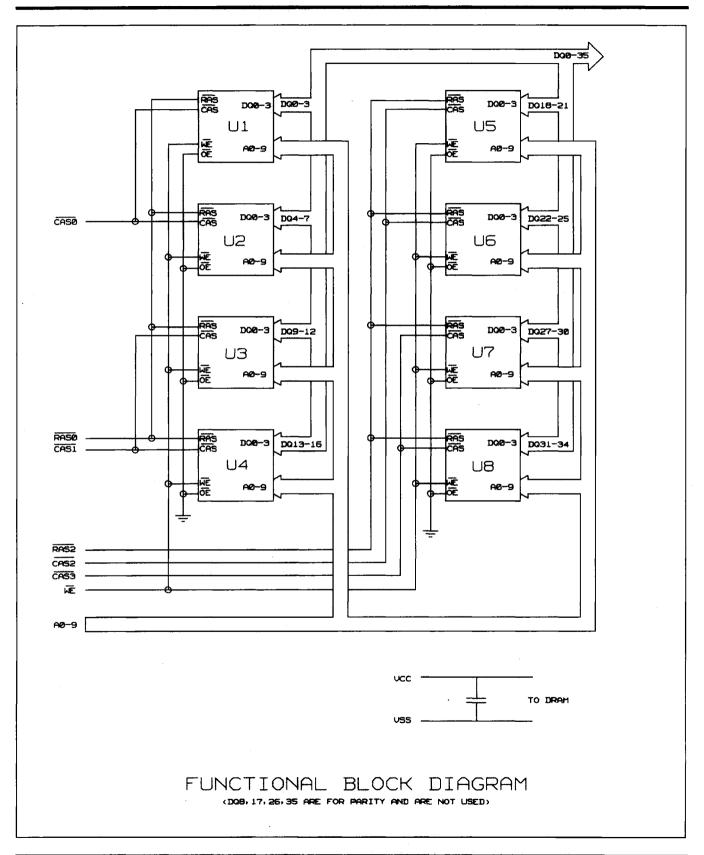
PIN SYMBOL	acompany (nash,							
· m o mpoc	60 me	70 nu						
PD1	VSS	VSS						
PD2	VSS	VSS						
PD3	NC	VSS						
PD4	NC	NC						



PIN CONFIGURATION

	IN CONTINUE										
#	Name	1#	l'ame		Carb :		beautifus and	14			Name
1	vss	13	A1	25	DQ24	37	NC	49	DQ9	61	DQ14
2	DQ0	14	A2	26	DQ7	38	NC	50	DQ27	62	DQ33
3	DQ18	15	A3	27	DQ25	39	VSS	51	DQ10	63	DQ15
4	DQ1	16	A4	28	A7	40	CASO	52	DQ28	64	DQ34
5	DQ19	17	A5	29	NC	41	CAS2	53	DQ11	65	DQ16
6	DQ2	18	A6	30	VCC	42	CAS3	54	DQ29	66	NC
7	DQ20	19	NC	31	A8	43	CAST	55	DQ12	67	PD1
8	DQ3	20	DQ4	32	A9	44	RASO	56	DQ30	68	PD2
9	DQ21	21	DQ22	33	NC	45	NC	57	DQ13	69	PD3
10	VCC	22	DQ5	34	RAS2	46	NC	58	DQ31	70	PD4
11	NC	23	DQ23	35	NC	47	WE	59	vcc	71	NC
12	A0	24	DQ6	36	NC	48	NC	60	DQ32	72	VSS







TRUTH TABLE

FUNCTION		FAS	DAS .	PE		COL AUTH	DATA IWOUT
Standby		Н	н⊸х	Х	X	х	Hi-Z
Read		L	L	Н	ROW	COL	Valid D _{out}
Early-Write		L	L	L	ROW	COL	Valid D _{IN}
Cost David Made Dood	1st Cycle	L	H→L	H	ROW	COL	Valid D _{out}
Fast Page Mode-Read	2nd Cycle	L	H→L	Н	N/A	COL	Valid D _{out}
Frak Drong Adada Milita	1st Cycle	L	H-L	L	ROW	COL	Valid D _{in}
Fast Page Mode-Write	2nd Cycle	L	H-L	L	N/A	COL	Valid D _{IN}
RAS-Only Refresh		L	Н	х	ROW	N/A	Hi-Z
LEdday Daforah	Read	L→H→L	L	Н	ROW	COL	Valid D _{out}
Hidden Refresh	Write	L→H→L	L	L	ROW	COL	Valid D _{IN}
CAS-Before-RAS Refresh)	H→L	L	Н	×	Х	Hi-Z

X:"H" or "L" D_{IN}:Data In D_{OUT}:Data Out Hi-Z:High Impedance N/A:Not Applicable

ABSOLUTE MAXIMUM RATINGS (Note 1,22)

SYMBO	L PARAMETER	RATINO	(Upper	HOTES .	
V _{cc}	Power Supply Voltage	-1.0 to 7.0	٧	2	
V _{IN}	Voltage on one Bin Beletive to V	-1.0 to 7.0	V	2	
V _{out}	Voltage on any Pin Relative to V _{ss}	-1.0 to 7.0	٧	2	
T _{opr}	Operating Temperature	0 to 70	°C		
T _{stg}	Storage Temperature	-55 to 125	°C		
PD	Power Dissipation	8.0	W	17,31	
los	Short Circuit Output Current	50	mA	17	



RECOMMENDED OPERATING CONDITIONS (T_A= 0 to 70 °C) (Note 2)

SYMBO	OL PARAMETER		16623	HANE.	Ulite	NOTES
V _{cc}	Supply Voltage	4.5	5.0	5.5	٧	
V _{ss}	Ground	0	0	0	٧	
V _{IH}	Input High Voltage	2.4	-	V _{cc} +1.0	٧	22
V _{IL}	Input Low Voltage	-1.0		0.8	V	22

T_A: Ambient temperature

CAPACITANCE (f = 1 MHz; T_A = 25 °C) (Note 22)

SYMB	OL PARAMETER	1,000	Chine	NOTES
C ₁₁	Input Capacitance (A0-A9)	48	pF	
C ₁₂	Input Capacitance (RASO,RAS2)	28	pF	
C ₁₃	Input Capacitance (CAS0~CAS3)	14	pF	
C _{I4}	Input Capacitance (WE)	56	pF	
Con	Output Capacitance (Data In/Out)	7	pF	

T_A: Ambient temperature



DC CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.) (Note 18,22)

SYMBOL	PARAMETER			tin.	WKX.	NOTES
l _{cc1}	OPERATING CURRENT: Ave Operating Current (RAS,CAS		60 ns	-	880	3,4,5,6,16
	$t_{RC(min)}, V_{CC} = V_{CC(max)})(mA)$		70 ns	-	800	
I _{CC2}	STANDBY CURRENT (TTL): Current (RAS=CAS=Vcc, Dat all other inputs =Vcc, V _{cc} =V _{cc}	a out is disabled (Hi-Z),	Don't Care	-	16	
I _{CC3}	RAS-ONLY REFRESH CURRENT: Average Power Supply Current, RAS-Only Mode (RAS, Address Cycling, CAS=V _{IH} @t _{RC} =t _{RC(min)} , V _{CC} =V _{CC(max)}) (mA)		60 ns	-	880	3,4,5,6,16, 31
			70 ns	-	800	
I _{CC4}	FAST PAGE MODE CURRENT: Average Power Supply Current, FPM (RAS=V _{IL} ,CAS, Address Cycling@ t _{PC} =t _{PC(min)} ,V _{CC} =V _{CC(max)}) (mA)		60 ns	-	880	3,4,5,7,16
			70 ns	-	800	
I _{ccs}	STANDBY CURRENT (CMOS Current (RAS=CAS=V _{CC} -0.2V (Hi-Z),V _{CC} = V _{CC(max)}) (mA)	Don't Care	-	8		
I _{CC6}	CAS-BEFORE-RAS, REFREE Power Supply Current, CAS-B		60 ns	•	880	3,4,5,6,16, 31
	(RAS,CAS Cycling@t _{RC} =t _{RC(mi}		70 ns	•	800	
I _{LI}	INPUT LEAKAGE CURRENT: Input Leakage	A0~A9, WE		-80	80	
	Current, any input (0≤V _{IN} ≤V _{cc} , all other pins not	RASO,RAS2		-40	40	
	under test=0V, V _{CC=} V _{CC(max)}) CAS0~			-20	20	
I _{LO}	OUTPUT LEAKAGE CURRENT: (Data Out is disabled (Hi-Z), 0≤V _{OUT} ≤V _{CC})(μA)			-10	10	
V _{OH}	OUTPUT HIGH LEVEL: Output "H" Level Voltage (I _{OUT} =-5mA) (V)			2.4	-	2
V _{OL}	OUTPUT LOW LEVEL: Output "L" Level Voltage (I _{OUT} =+4.2mA) (V)			•	0.4	2



AC CHARACTERISTICS

READ, WRITE, AND REFRESH CYCLES (COMMON PARAMETERS)

(Recommended operating conditions unless otherwise noted.) (Note 8,18)

	PARAMETER			70 ************************************	ne ilist.	NOTES
t _{RC}	Random READ or WRITE Cycle Time (ns)	110	-	130	-	
t _{RP}	RAS Precharge Time (ns)	40	-	50	-	
t _{ce}	CAS Precharge Time (ns)	10	-	10	-	
t _{RAS}	RAS Pulse Width (ns)	60	10000	70	10000	23
t _{CAS}	CAS Pulse Width (ns)	15	1000	20	10000	23
t _{ASR}	Row Address Setup Time (ns)	0	-	0	-	22
t _{RAH}	Row Address Hold Time (ns)	10	-	10	-	
t _{ASC}	Column Address Setup Time (ns)	0	•	0	-	22
t _{CAH}	Column Address Hold Time (ns)	15	-	15	-	22
t _{RCD}	RAS to CAS Delay Time (ns)	20	45	20	50	10
t _{RAD}	RAS to Col. Address Delay Time (ns)	15	30	15	35	15,23
t _{esh}	RAS Hold Time (ns)	15	-	20	-	22
t _{csh}	CAS Hold Time (ns)	60	-	70	-	
t _{CRP}	CAS to RAS Precharge Time (ns)	10	-	10	-	22
t _{RPC}	RAS Precharge to CAS hold Time (ns)	10	-	10	-	22
t _T	Transition Time (Rise and Fall) (ns)	3	30	3	30	22
t _{AR}	Column Address Hold Time Referenced to RAS (ns)	50	-	55	_	22



READ CYCLES (Note 8,18)

SYMBOL	PARAMETER	- 188 4	re Histori	70 NBN:	THE MALE.	NOTES
t _{RAC}	Access Time from RAS (ns)	-	60	-	70	9,10,15,30
t _{CAC}	Access Time from CAS (ns)	-	15	-	20	9,10,30
t _{AA}	Access Time from Address (ns)	-	30	-	35	9,15,30
t _{ACS}	Read Command Setup Time (ns)	0	-	0	-	22
t _{ach}	Read Command Hold Time to CAS (ns)	0	-	0	-	14,22
t _{RRH}	Read Command Hold Time to RAS (ns)	10	-	10	-	14,22
t _{RAL}	Column Address to RAS Lead Time(ns)	30	-	35	-	22
t _{CLZ}	CAS to Output in Low-Z (ns)	0	-	0	-	9,22
t _{ozc}	Data to CAS Low Delay Time (ns)	0	-	0	-	28
t _{CDD}	CAS High to Data Delay Time (ns)	15	-	20	-	27
t _{OFF}	Output Buffer Turn-Off Delay (ns)	0	15	0	20	12,24

WRITE CYCLES (Note 8,18)

	(1000 5,15)	80 na 70 na					
SYMBOL	PARAMETER	AUR.	TEE.	in.	. HAVE.	NOTES	
t _{wcs}	Write Command Set Up Time (ns)	0	-	0	-	13	
t _{wch}	Write Command Hold Time (ns)	15	-	15	-		
t _{wP}	Write Command Pulse Width (ns)	10	-	15	-	22	
t _{RWL}	Write Command to RAS Lead Time (ns)	15	-	20	-	22	
t _{cwL}	Write Command to CAS Lead Time (ns)	15	_	20	-	22	
t _{DS}	D _{IN} Setup Time (ns)	0	-	0	-	25	
t _{DH}	D _{IN} Hold Time (ns)	15	-	15	-	22,25	
t _{wcn}	Write Command Hold Time Referenced to RAS (ns)	50	_	55	-		
t _{DHR}	Data in Hold Time Referenced to RAS (ns)	50	<u>-</u>	55	-	22	



FAST PAGE MODE CYCLES (Note 8,18)

SYMBOL	PARAMETER	90 "4684.	ng MAX	70 1488 ,		NOTES
t _{PC}	Fast Page Mode Cycle Time (ns)	45	-	50	-	
t _{rasp}	Fast Page Mode RAS Pulse Width (ns)	65	100000	75	100000	22
t _{CPRH}	RAS Hold Time from CAS Precharge (ns)	35	-	40	-	22
t _{CPA}	Access Time from CAS Precharge (ns)	-	35	-	40	9,21,22,30
t _{CPW}	WE Delay Time From CAS Precharge (ns)	60	-	70	-	13

REFRESH CYCLE (Note 8,18)

REFRESH CYCLE (Note 8,18)						
SYMBOL	PARAMETER		THE STATE	70 144 4.	HAX.	NOTES
t _{CHR}	CAS Hold Time (CAS-before-RAS Refresh Cycle) (ns)	10	-	15	-	22
t _{csn}	CAS Setup Time (CAS-before-RAS Refresh Cycle) (ns)	10	•	10	-	
t _{WRP}	WE Setup Time (CAS-before-RAS Refresh Cycle) (ns)	10	•	10	-	22
t _{wah}	WE Hold Time (CAS-before-RAS Refresh Cycle) (ns)	10	-	10	-	22
t _{REF}	Refresh Period (1024 cycles) (ms)	+	16	•	16	



NOTES

- Permanent damage to the device may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional
 operation should be restricted to the conditions as detailed in this data sheet. Exposure to absolute maximum
 rating conditions for extended periods may affect reliability.
- 2. All voltages referenced to V_{ss}.
- 3. Icc is specified as an average current.
- 4. This parameter depends on output loading and/or cycle rates.
- 5. Specified values are obtained with the output open.
- 6. Address can be changed a maximum of once while RAS=V_{II}.
- 7. Address can be changed a maximum of once while CAS=V_{III}.
- 8. $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals. Transition time (t_T) is measured between $V_{IH(min)}$ and $V_{IL(max)}$, and is assumed to be 5ns for all inputs. All input signals must transit between V_{IH} and V_{IL} (or V_{IL} and V_{IH}) without slope reversal.
- 9. Measured with a load equivalent to 2 TTL loads and 100pF.
- 10. Operation within the $t_{RCD(max)}$ limit ensures that $t_{RAC(max)}$ can be met. $t_{RCD(max)}$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD(max)}$ limit, then access time is controlled exclusively by t_{CAC} .
- 11. Assumes that $t_{RCD} \ge t_{RCD(max)^3} t_{RAD} \le t_{RAD(max)^4}$
- 12. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL}.
- 13. This is a non-restrictive operating parameter. It is included in the data sheet as an electrical characteristic only. If twos > twos(min) the cycle is an early write cycle and the data out pins will remain high impedance (open circuit) for the duration of the cycle. If the above condition is not satisfied, the condition of the data out (at access time) is indeterminate.
- 14. Either t_{BCH} or t_{BBH} must be satisfied for a read cycle.
- 15. Operation within the t_{RAD(max)} limit ensures that t_{RAD(max)} can be met. t_{RAD(max)} is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD(max)} limit, then access time is controlled exclusively by t_{AA}.
- 16. Specified values are obtained with minimum cycle time.
- 17. Specified values are obtained with $T_A = 25$ °C.

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- 18. An initial pause of 200µs is required after power-up followed by a minimum of eight initialization cycles (any 8 CAS-before-RAS or RAS-only Refresh cycles with WE high) before proper device operation is assured. Also, any 8 CAS-before-RAS or RAS-only Refresh cycles with WE high are required after prolonged periods (greater than t_{REF}) of RAS inactivity before proper device operation is assured.
- 19. Measured with a load equivalent to 50pF and 500 ohms.
- 20. Write cycle is applicable instead of read cycle. Timing requirements for RAS, CAS and Address are the same for Hidden Refresh Write Cycle as that shown for Hidden Refresh Read Cycle. WE, D_{IN} and D_{OUT} for Hidden Refresh Write Cycle are the same as for Write Cycle.
- 21. t_{CPA} is access time from CAS precharge (that is caused by changing CAS from "L" to "H"). Therefore, if t_{CP} is long, then t_{CPA} is longer than t_{CPA(max)}.
- 22. Calculated based on data supplied by the DRAM manufacturer(s).
- 23. Maximum value is calculated based on data supplied by the DRAM manufacturer(s).
- 24. Minimum value is calculated based on data supplied by the DRAM manufacturer(s).
- 25. This parameter is referenced to the CAS leading edge in Early Write cycles and to the WE leading edge in Read-Modify-Write cycles.
- **26.** $V_{IN} = 0$ Volt.
- 27. Either t_{CDD} or t_{ODD} must be satisfied.
- 28. Either tozc or tozo must be satisfied.
- 29. t_{RASP(MIN)} is specified as two cycles of CAS input are performed.
- 30. The access time is limited by all four parameters t_{RAC} , t_{CAC} , t_{AA} , t_{CPA} .
- 31. This assumes all RAS (and all CAS for CBR refresh) are active.



For Timing Diagrams see "FPM Timing Diagrams" (Document No. 20432C).

Available from fax-on-demand and Website: http://www.celestica.com/memory/

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